

Title (en)
Packaging component and semiconductor package

Title (de)
Packungsanordnung und Halbleitergehäuse

Title (fr)
Dispositif d'emballage et boîtier semi-conducteur

Publication
EP 1480270 B1 20160720 (EN)

Application
EP 04010184 A 20040429

Priority
JP 2003145216 A 20030522

Abstract (en)
[origin: EP1480270A2] A packaging component used for constituting a package mounting a semiconductor element, and a semiconductor package using the packaging component. The packaging component has on at least a portion of the surface thereof a covered surface which is sealed with an insulating resin or on which an adhesive layer is applied, and the packaging component comprises a conductor substrate and an electrically conducting layer partly or entirely covering the surface thereof, and the electrically conducting layer comprises a rough-surface plated layer having a roughened surface profile on the covered surface. The packaging component includes, for example, a lead frame and a heat-radiating or heat-dissipating plate. <IMAGE>

IPC 8 full level
H01L 23/495 (2006.01); **H01L 23/50** (2006.01); **C25D 5/02** (2006.01); **C25D 5/12** (2006.01); **C25D 7/12** (2006.01); **H01L 23/433** (2006.01)

CPC (source: EP KR US)
A47J 27/13 (2013.01 - KR); **C25D 5/02** (2013.01 - EP US); **C25D 5/12** (2013.01 - EP US); **C25D 5/605** (2020.08 - EP US); **C25D 5/611** (2020.08 - EP US); **C25D 5/617** (2020.08 - EP US); **C25D 5/627** (2020.08 - EP US); **H01L 23/49582** (2013.01 - EP US); **H01L 24/48** (2013.01 - EP US); **H05B 6/6408** (2013.01 - KR); **H01L 23/4334** (2013.01 - EP US); **H01L 24/45** (2013.01 - EP US); **H01L 2224/16** (2013.01 - EP US); **H01L 2224/45144** (2013.01 - EP US); **H01L 2224/48091** (2013.01 - EP US); **H01L 2224/48247** (2013.01 - EP US); **H01L 2224/484** (2013.01 - EP US); **H01L 2224/48599** (2013.01 - EP US); **H01L 2224/48639** (2013.01 - EP US); **H01L 2224/48664** (2013.01 - EP US); **H01L 2224/73204** (2013.01 - EP US); **H01L 2224/73253** (2013.01 - EP US); **H01L 2224/85439** (2013.01 - EP US); **H01L 2224/85464** (2013.01 - EP US); **H01L 2924/00014** (2013.01 - EP US); **H01L 2924/01004** (2013.01 - US); **H01L 2924/01005** (2013.01 - US); **H01L 2924/01006** (2013.01 - US); **H01L 2924/01011** (2013.01 - US); **H01L 2924/01013** (2013.01 - US); **H01L 2924/01015** (2013.01 - US); **H01L 2924/01023** (2013.01 - US); **H01L 2924/01024** (2013.01 - US); **H01L 2924/01028** (2013.01 - US); **H01L 2924/01029** (2013.01 - US); **H01L 2924/01047** (2013.01 - US); **H01L 2924/0105** (2013.01 - US); **H01L 2924/01078** (2013.01 - US); **H01L 2924/01079** (2013.01 - US); **H01L 2924/01084** (2013.01 - US); **H01L 2924/01088** (2013.01 - US); **H01L 2924/014** (2013.01 - EP US); **H01L 2924/12042** (2013.01 - EP US); **H01L 2924/14** (2013.01 - EP US); **H01L 2924/15311** (2013.01 - EP US); **H01L 2924/15747** (2013.01 - EP US); **H01L 2924/16152** (2013.01 - EP US); **H01L 2924/181** (2013.01 - EP US); **H01L 2924/18301** (2013.01 - EP US); **H01L 2924/3025** (2013.01 - EP US)

C-Set (source: EP US)
1. **H01L 2224/45144 + H01L 2924/00014**
2. **H01L 2924/181 + H01L 2924/00012**
3. **H01L 2924/00014 + H01L 2224/0401**
4. **H01L 2224/484 + H01L 2924/00014**
5. **H01L 2224/48091 + H01L 2924/00014**
6. **H01L 2924/16152 + H01L 2224/73253**
7. **H01L 2924/15747 + H01L 2924/00**
8. **H01L 2224/48639 + H01L 2924/00**
9. **H01L 2224/48664 + H01L 2924/00**
10. **H01L 2924/12042 + H01L 2924/00**
11. **H01L 2224/48091 + H01L 2924/00012**

Cited by
EP3358048A4; EP3285295A1; IT201600086321A1; US10400347B2; TWI696729B

Designated contracting state (EPC)
DE FR IT NL

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EP 1480270 A2 20041124; EP 1480270 A3 20050713; EP 1480270 B1 20160720; CN 100433300 C 20081112; CN 1574300 A 20050202; JP 2004349497 A 20041209; JP 3841768 B2 20061101; KR 101069198 B1 20110930; KR 20040101038 A 20041202; MY 141960 A 20100730; TW 200503192 A 20050116; TW I351078 B 20111021; US 2004232534 A1 20041125; US 7190057 B2 20070313

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EP 04010184 A 20040429; CN 200410042368 A 20040520; JP 2003145216 A 20030522; KR 20040036130 A 20040520; MY PI20041695 A 20040507; TW 93112236 A 20040430; US 83500704 A 20040430